

« Le GaN dans les systèmes militaires »

« GaN in military systems »

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Summary

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- Substrates and Epitaxy
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DGA : OUR MISSIONS

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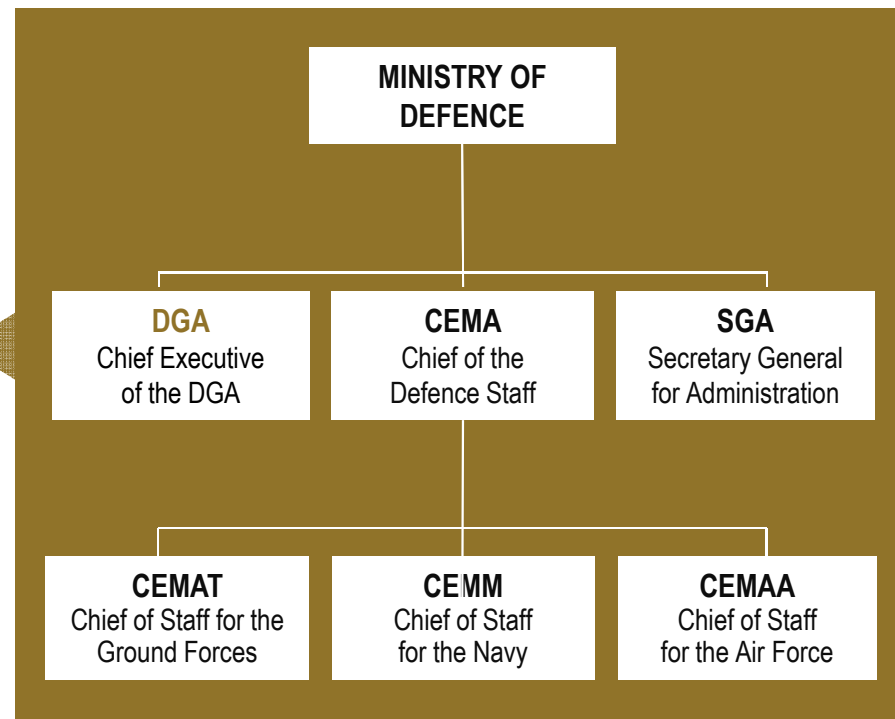
DEFENCE PROCUREMENT AGENCY

Equipping
the Armed Forces

Preparing the future
of Defence systems

Promoting Defence
equipment exports

At the core of the Ministry of Defence



Components activities at DGA

- Part of Technical Directorate
- All Electronic and opto-electronics components
- 40 persons in Bagneux (South of Paris) and Bruz (near Rennes)
- 13 persons working on microwave components and systems
- Expertise, technology analysis and RF characterisation



GaN History at DGA

- Late 1990's GaN break-through is detected by DGA
- 2001 : First DGA contract to research labs launched
- 2003 : First military European conference (MoD's, Industry and research Labs) in Stockholm
 - MoDs convinced that they need to support the development of GaN microwave technology to make it available in Europe, without access restriction
- 2005 : Biggest EDA project (Korrigan) on components funded by 7 European MoD's is started
- 2006 : UMS started industrialisation
- 2011 : UMS GH50 technology qualified

GaN advantages versus GaAs

- Firstly : transistors power density
 - Higher power T/R for radars
 - Higher power for jamming
 - Smaller circuits: lowering of the €/W cost
- Wide band capability for Electronic Warfare
- Robustness
 - LNA without limiter in radar antennas
 - Radiations
- Higher operating T_j

GaN necessary improvements

- HPA X band MMIC current capability
 - GaAs $\sim 20\text{mm}^2$ 10W PAE 40%
 - GaN $\sim 20\text{mm}^2$ $>20\text{W}$ PAE 50%
- Without PAE improvement, the potential of this technology can't be exploited due to thermal constraints
- PAE and packaging with high thermal dissipation capability are still to be improved
- TJ 225°C qualification

GaN Circuits – next step

- T/R module with GaN / w/o GaAs
 - Robust LNA
 - NF ~ GaAs LNA
 - High linearity
 - >40dBm without damage
 - Recovery time !!!
 - Driver
- Other circuits
 - Power switches
 - Mixer (Higher compression point)
 - ...

Substrates and Epitaxy (1/2)

- SiC substrates
 - Cristal compatibility with GaN
 - Good thermal propriety
 - But expensive compared to Si
 - Up to now one source (US) is delivering the majority of the 4 inches quality substrates
 - → MoDs support to have an European alternative : EDA MANGA project
- Si substrates
 - Not chosen in a first step :
 - Lower epitaxy quality
 - Thermal constraints for L to Ku band power devices
 - Solution for lower power devices at higher frequencies assuming the lossy lines issue is solved.

Substrates and Epitaxy (2/2)

- Epitaxy
 - A European substrates provider won't be sufficient without a European Epitaxy provider to guarantee the availability of the GaN technology material for military application
 - After Korrigan the main technical approach exhibiting good result was MOCVD
 - European MoDs have the objective to make this European source emerging

European Industrial Base

- Substrates
 - Norstel (Sw), SiCrystal (Ge)
- Epitaxy
 - IQE (UK), EpiGaN (B), Classic (Sw)
- GaN process
 - Ommic (Fr), Selex SI (It), UMS (Fr/Ge)

GaN Military Applications

- The main applications are those which need high power in a small volume
 - Active antennas radar
 - Jamming
 - Seeker
 - Telecom
 - Military Frequency band : VHF, UHF, L to Ka
- SATCOM
 - A growing need waiting for European technology
 - Common Space and military need
 - Ka band

GaN Military Market

- Deployment of GaN in progress for all the military applications in all the frequency bands
- Nevertheless European military market will not be large enough to feed the GaN suppliers
- ESA in phase with MoDs on the need
 - Regular meetings and workshops with ESA allow the alignment of both ESA and MoDs strategy
- Still waiting for the volume Telecom market



Conclusion

- Strong effort from MoDs to develop GaN technology in Europe
 - Technology now available
 - Material availability to be achieved
- Thermal constraints still to be mitigated (PAE, T_j , packaging)
- Ka-band technology is the next step
- After HPA, need for LNA, Mixer....